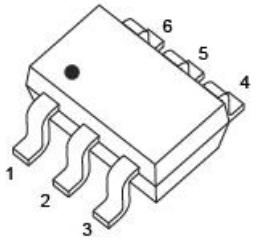
PNP General Purpose Amplifier

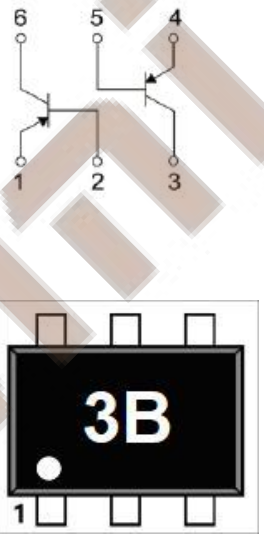
General Description

V_{CEO}	I_C	$V_{CE(sat)}$	f_T	T_{jMax}
-65V	-100mA	-0.3V@IC=-100mA	100MHz	150℃



Features

- SOT363 Package
- Epoxy meets UL-94 V-0 flammability rating and halogen free
- Moisture Sensitivity Level 3
- High temperature soldering guaranteed 260℃/10seconds at terminals



Package Marking and Ordering Information

Product ID	Package	Marking	Qty(PCS)
BC856BS	SOT-363	3B	3000

Absolute Maximum Ratings (Ta=25℃ unless otherwise noted)

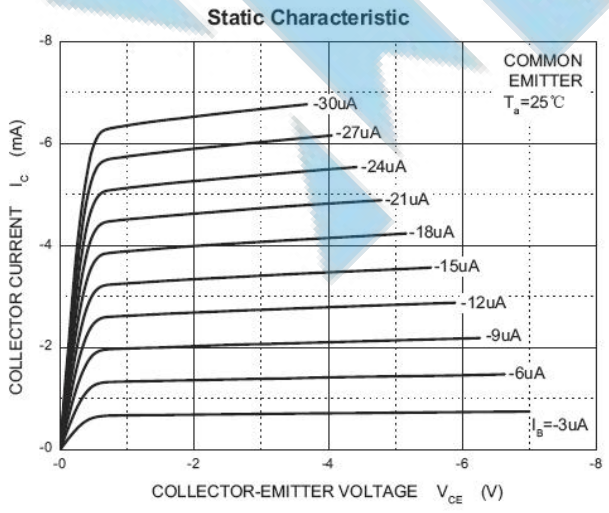
Parameter	Symbols	Value	Unit
Collector-Base Voltage	VCBO	-80	V
Collector-Emitter Voltage	VCEO	-65	V
Emitter -Base Voltage	VEBO	-5	V
Collector Current-Continuous	IC	-100	mA
Collector Power Dissipation	PC	200	mW
Junction Temperature	Tj	150	℃
Storage Temperature	Tstg	-55-+150	℃
Thermal resistance From junction to ambient	RθJA	625	℃/W

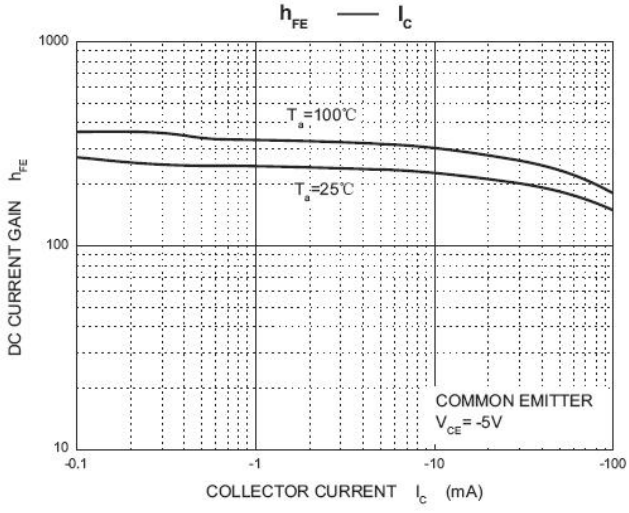
Electrical Characteristics(Ta=25℃ unless otherwise noted)

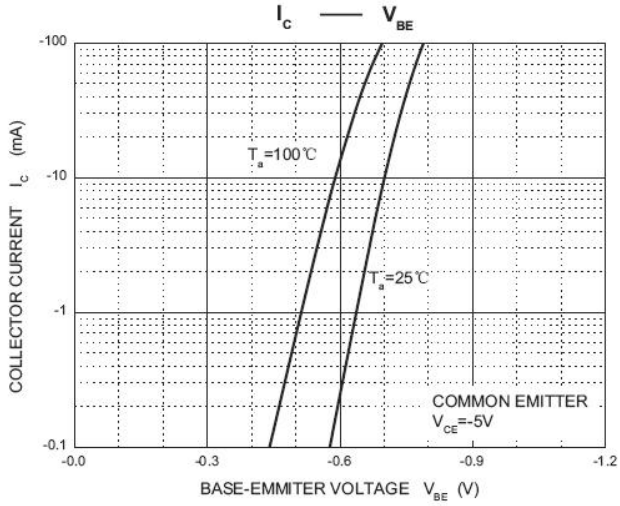
Parameter	Symbols	Test Condition	Limits			Unit
			Min	Typ	Max	
Collector-base breakdown voltage	V(BR)CBO	IC=-10uA, IE=0	-80			V
Collector-emitter breakdown voltage	V(BR)CEO	IC=-10mA, IB=0	-65			V
Emitter-base breakdown voltage	V(BR)EBO	IE=-10uA, IC=0	-5			V
Collector cut-off current	ICBO	VCB=-30V, IE=0			-15	nA
Emitter cut-off current	IEBO	VEB=-5V, IC=0			-100	nA
DC current gain	hFE	VCE=-5V, IC=-2mA	220		475	
Collector-emitter saturation voltage	VCE(sat)	IC=-10mA, IB=-0.5mA			-0.1	V
		IC=-100mA, IB=-5mA			-0.3	V
Base -emitter voltage	VBE	IC=-10mA, IB=-0.5mA		0.7		V
Transition frequency	fT	VCE=-5V, IC=-10mA,f=100MHz	100			MHz
Collector output capacitance	Cob	VCB=-10V, IE=0, f=1MHz			2.5	pF

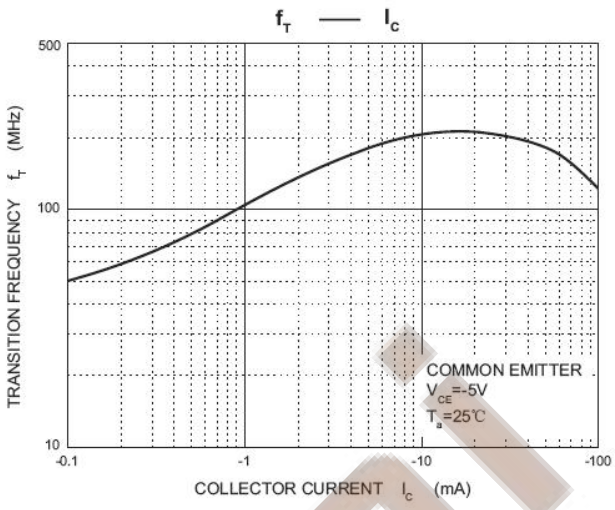
*Pulse test: pulse width≤300us,duty cycle≤2.0%

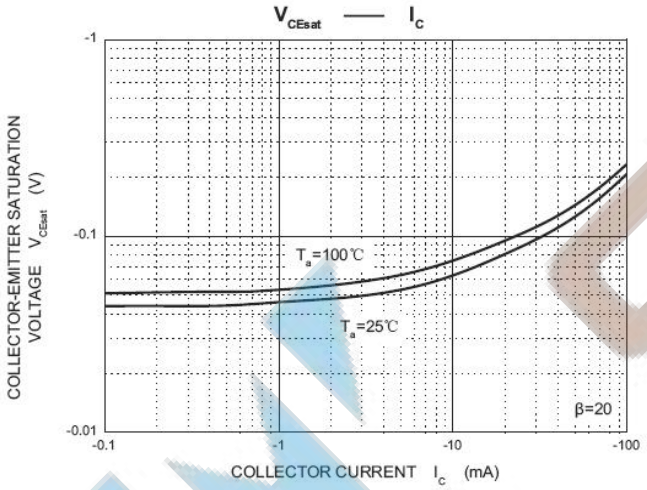
Typical characteristics

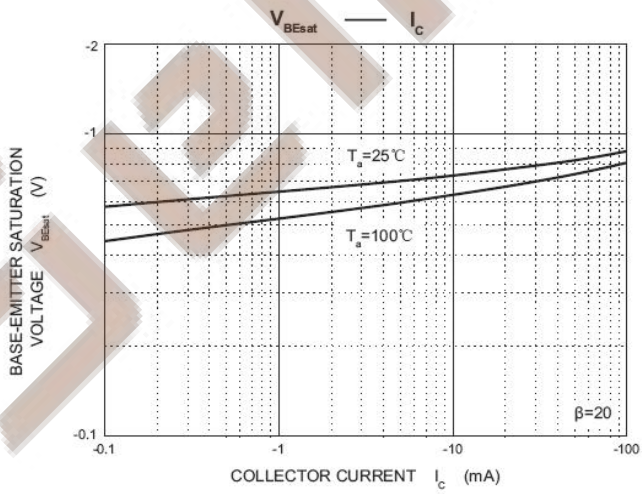


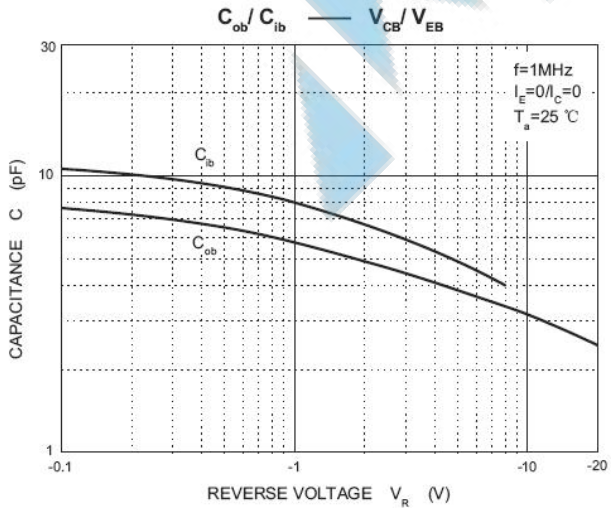


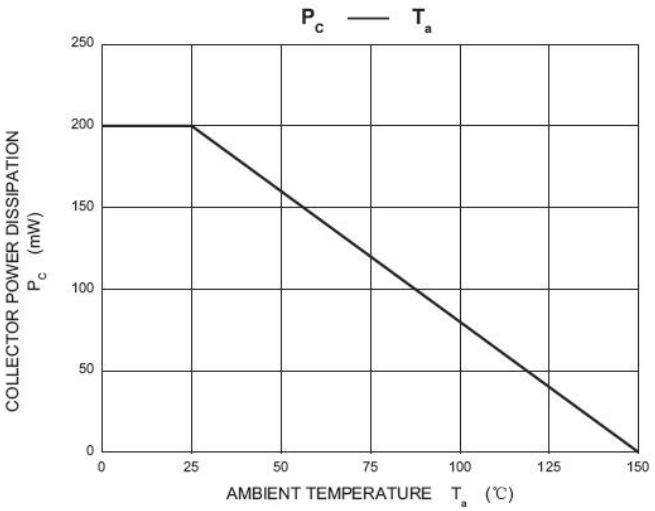

I_C — V_{BE}
COLLECTOR CURRENT I_C (mA)
-100
-10
-1
-0.1
T_a=100℃
T_a=25℃
COMMON EMITTER
V_{CE}=-5V
-0.0
-0.3
-0.6
-0.9
-1.2
BASE-EMMITER VOLTAGE V_{BE} (V)


f_T — I_C
TRANSITION FREQUENCY f_T (MHz)
500
100
10
COMMON EMITTER
V_{CE}=-5V
T_a=25℃
-0.1
-1
-10
-100
COLLECTOR CURRENT I_C (mA)


V_{CEsat} — I_C
COLLECTOR-EMITTER SATURATION VOLTAGE V_{CEsat} (V)
-1
-0.1
-0.01
T_a=100℃
T_a=25℃
β=20
-0.1
-1
-10
-100
COLLECTOR CURRENT I_C (mA)

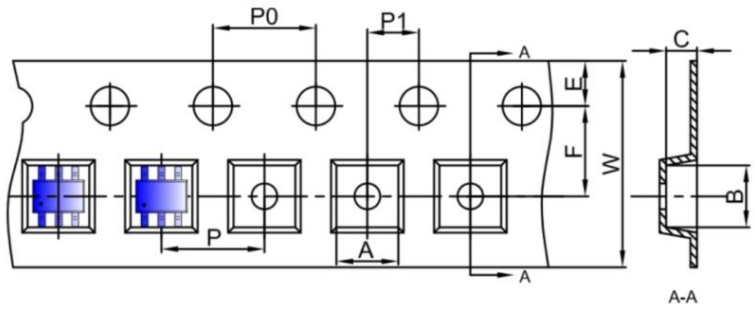

V_{BEsat} — I_C
BASE-EMITTER SATURATION VOLTAGE V_{BEsat} (V)
-2
-1
-0.1
T_a=25℃
T_a=100℃
β=20
-0.1
-1
-10
-100
COLLECTOR CURRENT I_C (mA)


C_{ob}/ C_{ib} — V_{CB}/ V_{EB}
CAPACITANCE C (pF)
30
10
1
f=1MHz
I_E=0/I_C=0
T_a=25 ℃
C_{ib}
C_{ob}
-0.1
-1
-10
-20
REVERSE VOLTAGE V_R (V)

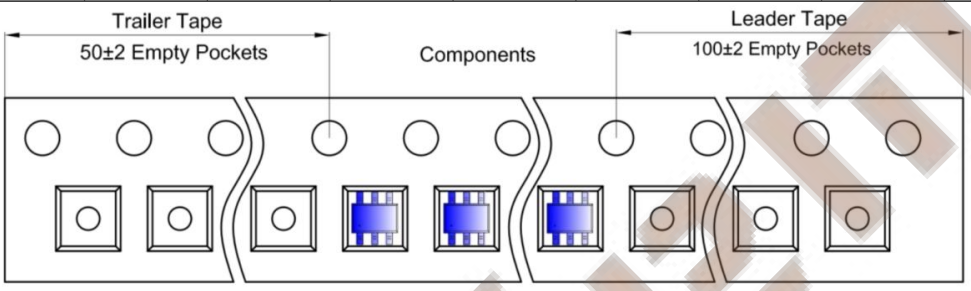

P_C — T_a
COLLECTOR POWER DISSIPATION P_C (mW)
250
200
150
100
50
0
0
25
50
75
100
125
150
AMBIENT TEMPERATURE T_a (℃)

Package Information

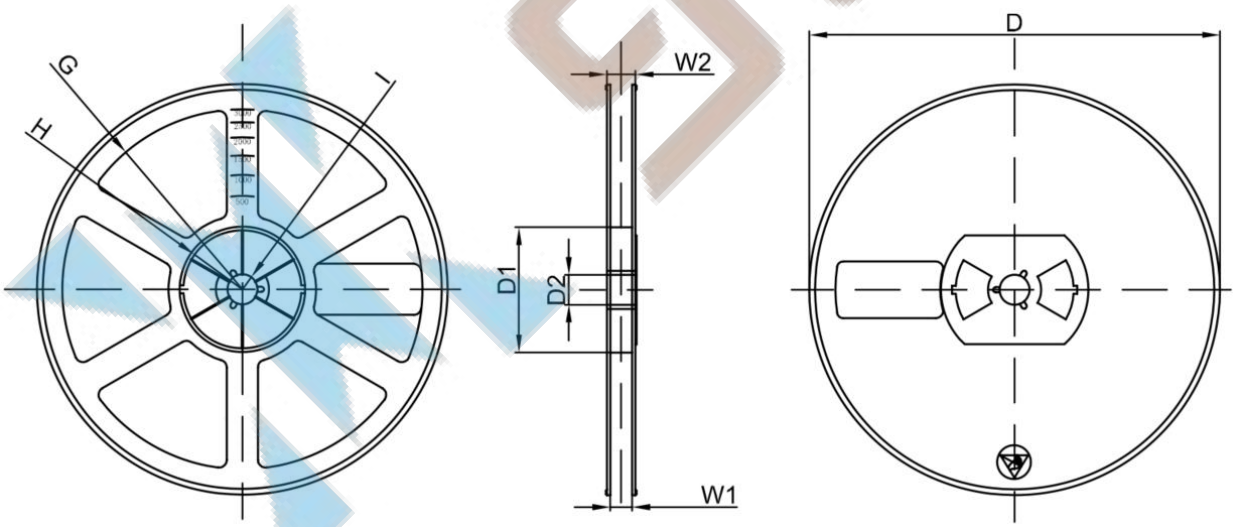
Carrier Dimension(mm)



Dimensions are in millimeter										
Pkg Type	A	B	C	d	E	F	P0	P	P1	W
SOT-363	2.25	2.55	1.20	Ø1.50	1.75	3.50	4.00	4.00	2.00	8.00



Reel Dimension(mm)



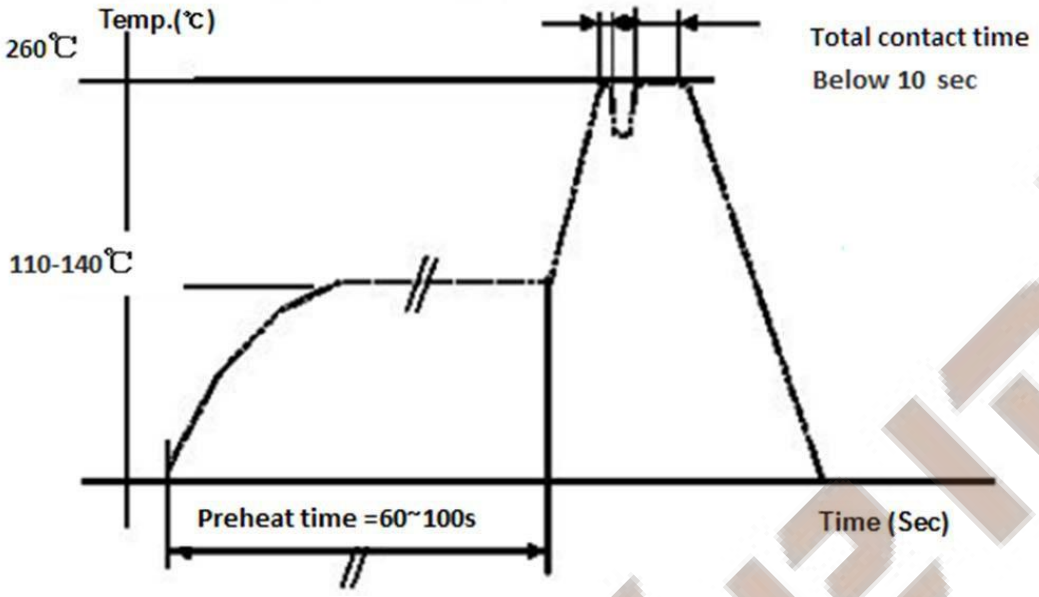
Reel Option	D	D1	D2	G	H	I	W1	W2
7"Dia	Φ178.00	54.40	13.00	R78.00	R25.60	R6.50	9.50	12.30
Tolerance	±2	±1	±1	±1	±1	±1	±1	±1

Package Specifications

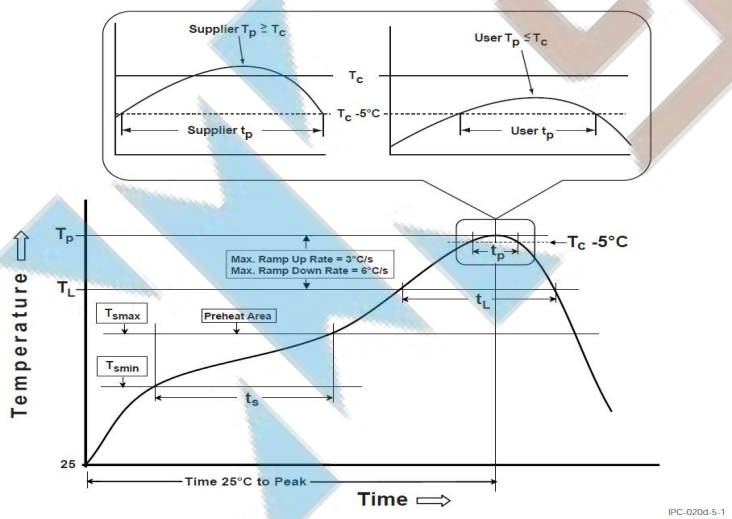
Package	Reel Size	Reel DIA. (mm)	Q'TY/Reel (Kpcs)	Box Size (mm)	QTY/Box (Kpcs)	Carton Size (mm)	Q'TY/Carton (Kpcs)
SOT363	7'	178	3	210*208*203	45	440*400*230	180

Recommended Soldering Profile for Rectifier Diodes (Pb Free)

a) Wave Soldering Profile



b) Reflow Soldering Profile (Pb Free Application), refer to IPC/JEDEC J-STD-020

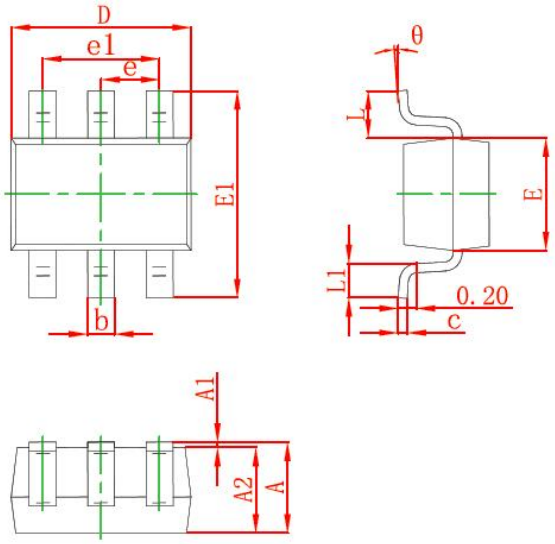


Preheat/Soak Temperature Min (Tsmin) Temperature Max (Tsmax) Time (ts) from (Tsmin to Tsmax)	50 °C 200 °C 60-120 seconds
Melting Point of Solder (Sn Ag Cu)	217℃
Ramp-up Rate to 217℃(Melting Point of Solder)	3℃/sec
Time at Temp.>217℃ (Melting Point of Solder)	60~150 Sec
Peak Temperature	255±5℃
Time within 5℃below Peak Temp.	20~40 Sec
Cooling Rate	6℃/sec (max)
Time from 25℃ to Peak Temp.	8min (max)

c) Manual Soldering

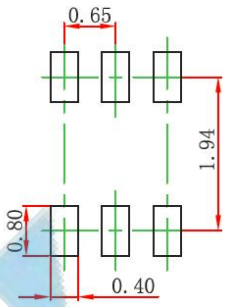
When using an electric soldering iron for manual soldering, it is recommended that the temperature does not exceed 300°C and the soldering time is less than 10 seconds.

Package Mechanical Data



Symbol	Dimensions In Millimeters	
	Min	Max
A	0.900	1.100
A1	0.000	0.100
A2	0.900	1.000
b	0.150	0.350
c	0.100	0.150
D	2.000	2.200
E	1.150	1.350
E1	2.150	2.400
e	0.650 TYP	
e1	1.200	1.400
L	0.525 REF	
L1	0.260	0.460
θ	0°	8°

Suggested Pad Layout



Note:
1.Controlling dimension:in millimeters.
2.General tolerance:±0.05mm.
3.The pad layout is for reference purposes only.

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